

# Material Composition Specification

CM Case

Pb (lead)-free plating\*



Device average mass ..... **3.0 g**

Fluctuation margin ..... **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.52%	15.59	Si	7440-21-3	0.51%	15.56	5,187
				Au	7440-57-5	0.01%	0.03	10
leadframe	copper	36.64%	1099	Cu	7440-50-8	36.64%	1099	366,353
die attach	high temperature solder	0.45%	13.61	Pb	7439-92-1	<0.001%	0.002	1
				Sn	7440-31-5	0.45%	13.608	4,536
encapsulation	EMC	60.83%	1825	epoxy resin	Proprietary	60.83%	1825	608,333
plating*	tin lead process	1.56%	46.74	Sn	74401-31-5	1.25%	37.40	12,464
				Pb	7439-92-1	0.31%	9.34	3,116
	100% tin process	1.56%	46.74	Sn	7440-31-5	1.56%	46.74	15,580

\*Specify Lead-Free when ordering 100% tin (Pb-free) plating.

Disclaimer

The information provided in this Material Composition data sheet is, to our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.